

**Protective film material for laser processing and wafer
processing method using the protective film material**

ABSTRACT

A protective film material for laser processing comprising a solution of a water-soluble adhesive and a water-soluble laser beam absorbent added to adjust absorbance at a wavelength of 355 nm (absorbance as calculated as a 200-times diluted solution) to 0.3 to 3. This protective film effectively

absorbs an irradiated laser beam, reduces generation of debris during laser beam irradiation, and can be removed by washing with water after completion of the laser processing treatment, thereby providing reliable processing. The water-soluble adhesive is preferably a blend of polyvinyl alcohol and poly-N-vinyl acetamide, which are preferably blended at a ratio of 100 to 200:1 in terms of amounts of respective components.

Fig. 1A